Contact Resistance Engineering in MoS₂ using **Hexagonal Boron Nitride**

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Abstract

Molybdenum disulphide (MoS₂), one of the most widely applicable transition metal dichalcogenide (TMD) is known to have high electron mobility at room temperature as well as optical property for monolayer. The band gap of single layer MoS₂ shows direct transition which values ~1.8 eV [1] is believed to be the source of its rectifying behaviour. MoS₂ shows Schottky behaviour when it is electrically contacted to metal by forming Schottky barrier (SB) at metal/MoS₂ interface. The potential barrier at the interface is directly related to contact resistance which should be minimized to achieve lower power consumption for high device performance. Many efforts were reported to engineer contact resistance for MoS₂ by adopting low work function metal for contact [2], doping the channel material with molecular dopant [3], transferring conductive layer at the contact/channel interface [4] and introducing thin insulating material on top of the channel [5]. In this study, we used centimetre-scale synthesized hexagonal boron nitride (hBN) on top of the MoS₂ channel layer in order to take advantage of absence of fermi level pinning which is considered to be a main reason of forming high Schottky barrier at the interface.

References

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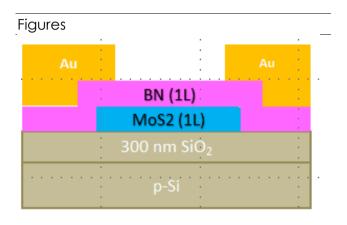


Figure 1: Atomically thin insulator is inserted between MoS₂ channel and contact metal.

